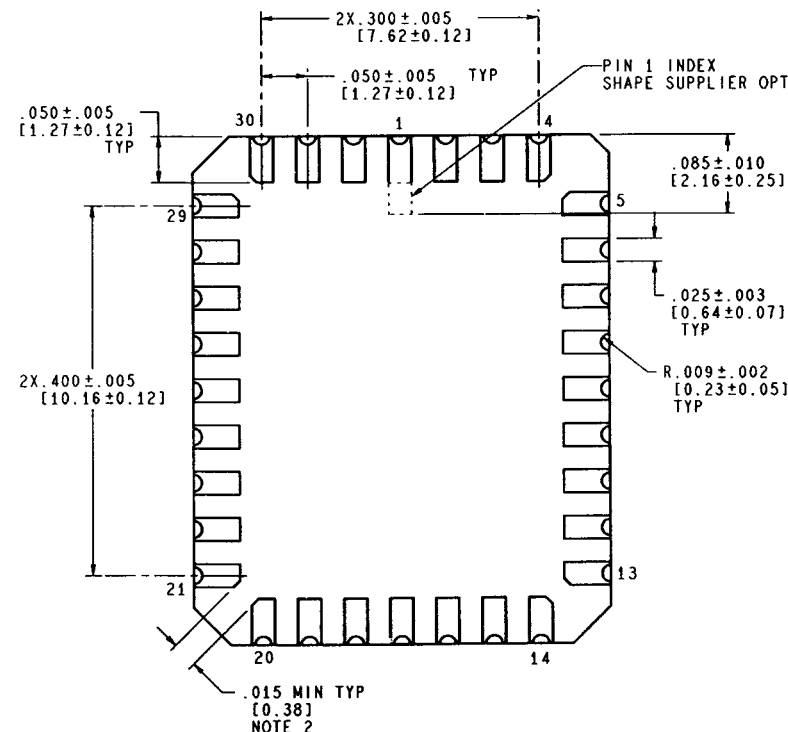
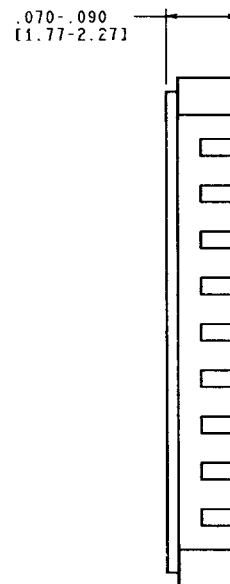
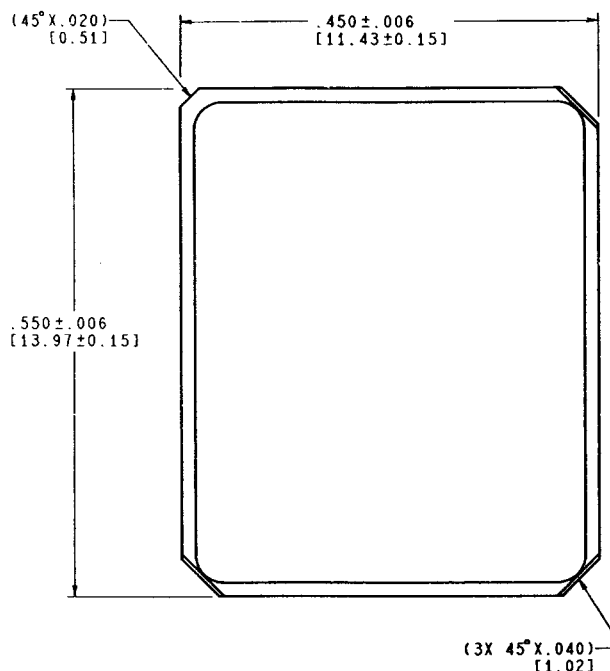


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP
A	RELEASE TO DOCUMENT CONTROL	11115	01/26/96	TL7



CONTROLLING DIMENSION IS INCH
VALUE IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

- a) 50 MICROINCHES/ 12.7 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICROINCHES/ 1.27-8.89 MICROMETERS NICKEL.
- b) SOLDER DIP THICKNESS PER LATEST REVISION OF MIL-STD-1835.

2. CORNER PADS MAY HAVE A 45° X .020 IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015 IN/0.38mm DIMENSION.

3. REFERENCE JEDEC REGISTRATION MO-041, VARIATION AB, DATED FEB 1995.

**MIL-PRF-38535
CONFIGURATION CONTROL**

APPROVALS		DATE		National Semiconductor	
T. LEQUANG		01/26/96		2000 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAFT		01/26/96		LEADLESS CHIP CARRIER, TYPE E, 32 TERMINAL	
1/26/96		1/26/96		SCALE N/A SIZE C DRAWING NUMBER MKT-EA32B REV A	
PROJECTION		DO NOT SCALE DRAWING		SHEET 1 of 1	